

# OL-PEMI8CSP\_RW\_P

Wafer level chip-size package; 20 bumps (8-4-8)

8 June 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package body material type</b>	X (other)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-7-2011
<b>Manufacturer package code</b>	WLCSP20

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.11	-	3.16	3.21	mm
E	package width	1	-	1.05	1.1	mm
A	seated height	0.57	-	0.61	0.65	mm
A <sub>2</sub>	package height	0.39	-	0.41	0.43	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	

## 2. Package outline

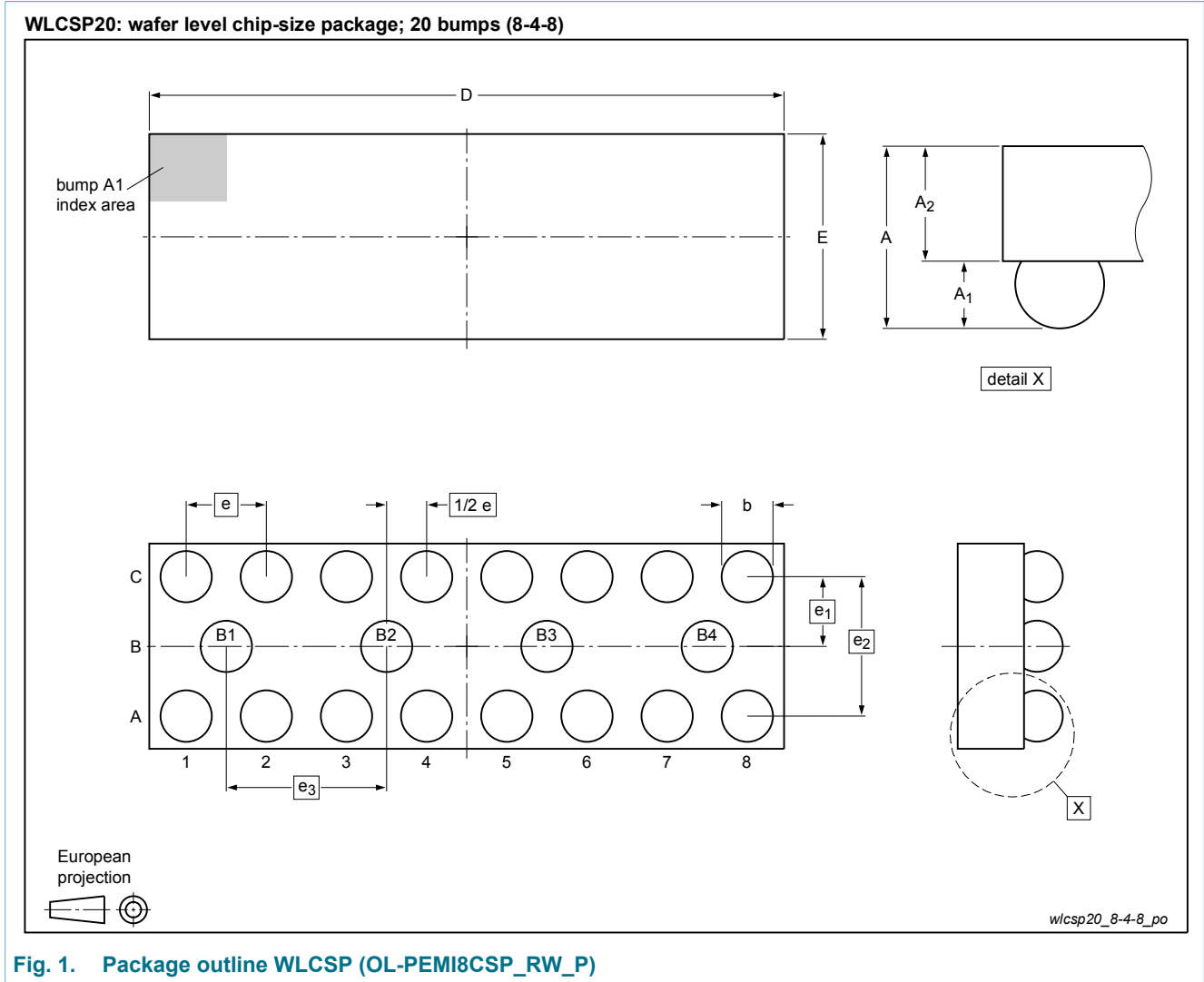


Fig. 1. Package outline WLCSP (OL-PEMI8CSP\_RW\_P)

### 3. Legal information

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